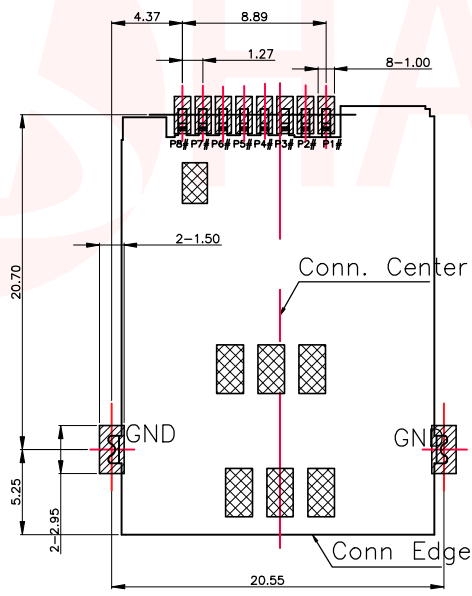
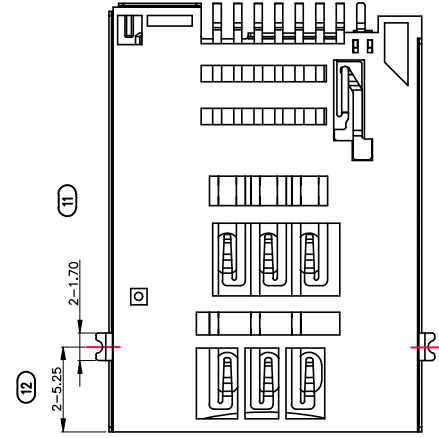
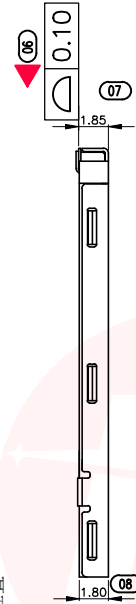
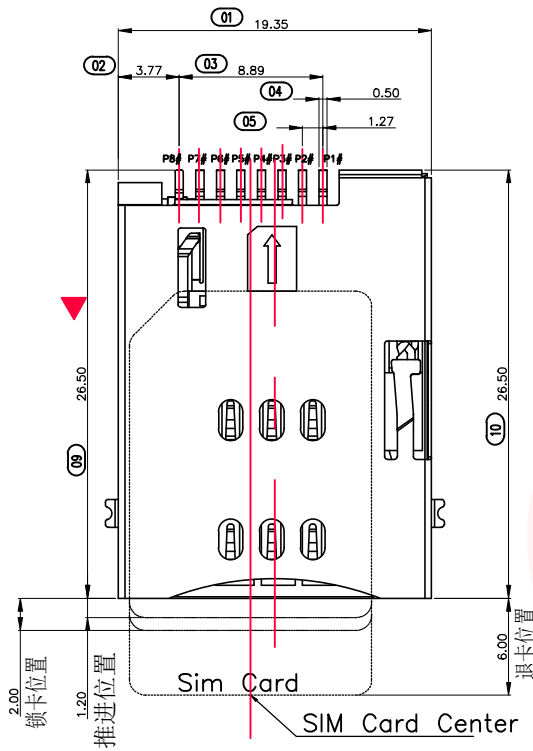




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL

RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA

NOTES:

MATERIAL:

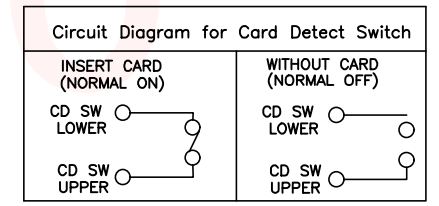
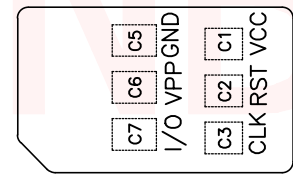
Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy
CD PIN: Copper Alloy
Shell: STAINLESS

PLATING:

Contact: Plated Ni, contact point gold plated G/F, welding feet Matte tin
Shell: Plated Ni Overall Plated G/F Selective Contact Area
CD PIN: Plated Ni, tin feet, contact point brush gold

Electrical:

Current Rating :0.5A AC/DC max.
Voltage Rating :30V AC/DC
Ambient Temperature Range :-20°C~+60°C
Storage Temperature Range :-40°C~+85°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500VDC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°

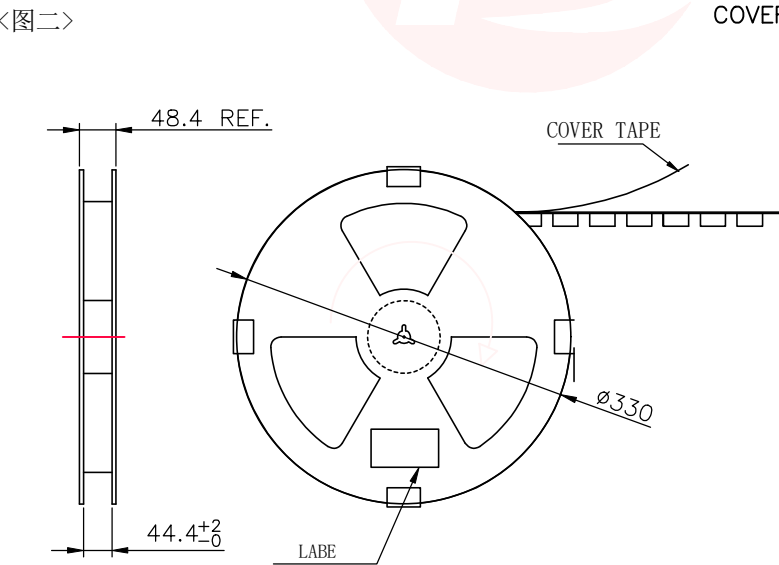
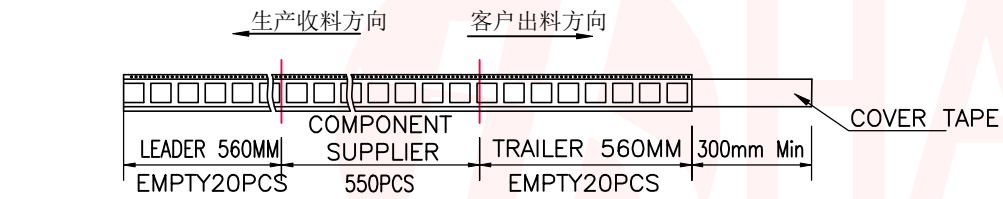
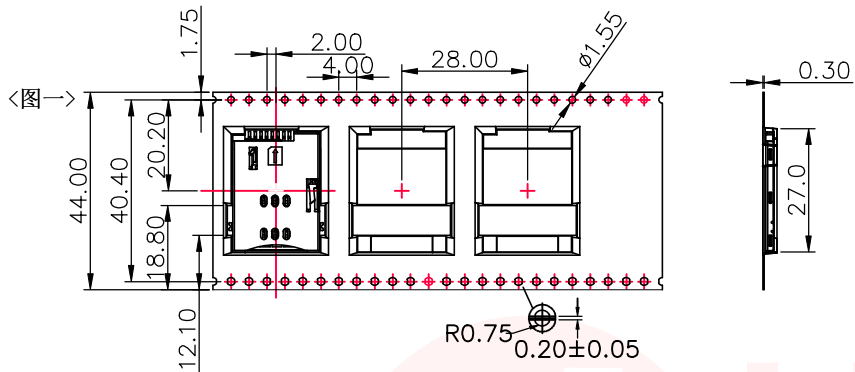


SIM 示意图
芯片面朝下视图

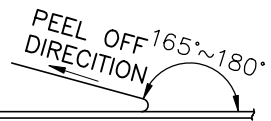
UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE	SIM PUSH 1.8H 脚距5.25客户图		
X :±0.30	X :±2°	DWN	xiong	PART NO. SIM-1001-P8	
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1	UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4	SHEET:10F 1
		REV: A4			
CUSTOMER COPY					



REV.	ECN NO OR DESCRIPTION	REVISED	DATE



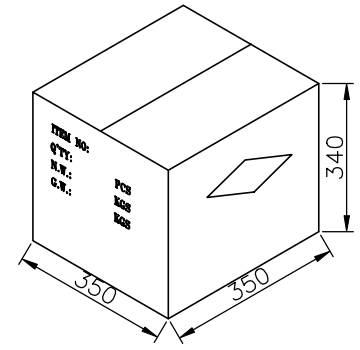
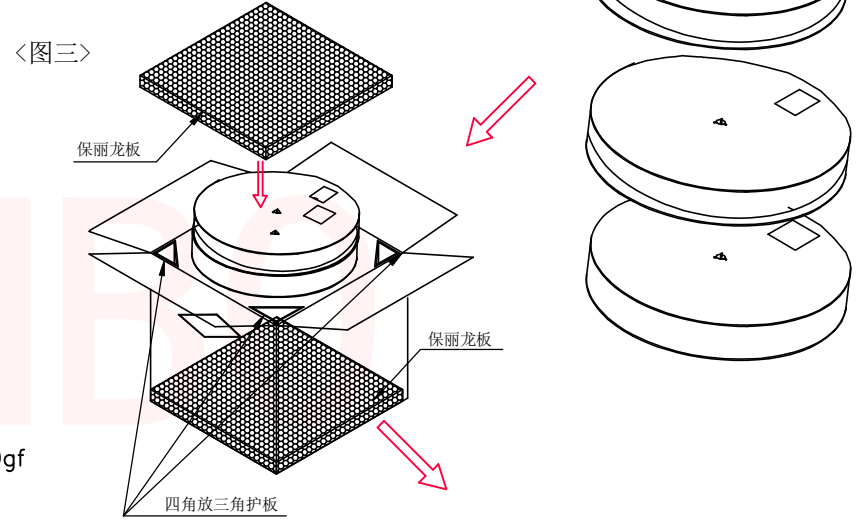
COVER TAPE PEELING FORCE: 20gf~120gf



- NOTE:
1. 依<图一>示放置产品于下载中, 每穴放置1PCS产品.
 2. 包装机包好后, 在REEL的个等分点贴上胶带, 以防止REEL张开, 每REEL贴1PCS标签, 如<图二>示
 3. 包装数量见如<TABLE 1>示
 4. 包装成箱见如<图三>示
箱底放保丽龙板, 再依次将指定数量的卷装产品放入箱内, 四角分别放入四个三角护板, 最上层再放上保丽龙板.
 5. 封箱, 在封好的纸箱上按客户要求写上料号, 数量等

<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300



UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD		
DECIMALS:	ANGLES:	TITLE SIM PUSH 1.8H 脚距5.25客户图		
X :±0.30	X :±2°	DWN	xiong	PART NO. SIM-1001-P8
X.X :±0.20	X.X :±1°	CHKD	lee	SCALE:1:1 UNIT: mm
X.XX :±0.10		APVD	wang	SIZE: A4 SHEET:10F 1 REV: A4
CUSTOMER COPY				

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[DM3AT-SF-PEJM5\(41\)](#) [IC11S-BUR-PNEJL\(71\)](#) [252-0144-000](#) [2041353-2](#) [308-DS1P0811-192](#) [HM2P09PDR360N9LF](#) [10014744-011TLF](#)
[11327-001](#) [11327-002](#) [617230001](#) [NX1-32T-KT3K\(05\)](#) [N7E50-U516RB-50-SIN0005](#) [68-580163-21S](#) [125A-78C00](#) [CCM03-3109 B LFT](#)
[2309923-1](#) [61126-050CAHLF](#) [IC1GA-68PD-1.27DS-EJ\(72\)](#) [GTFP08432B1HR](#) [SCE2MSDZN76A121SN](#) [10014744-011ALF](#) [10014744-](#)
[011LF](#) [10057542-1211FLF](#) [10067972-000LF](#) [10067972-050LF](#) [10122302-20110LF](#) [G85D1162022HHR](#) [MUP-C7809-1](#) [NANO SIM 7P](#)
[H1.37](#) [MICRO SIM 7P H1.35](#) [TF-CARD H1.8 SY](#) [MICRO SIM 6P H1.35](#) [TF-CARD H1.8](#) [TF-115Y-BCP9](#) [TF-115YY-ACP9](#) [SMN-309-](#)
[ARP6](#) [TF-115Y-ACP9](#) [TF-108-ARP10](#) [SMN-303S-ACP7](#) [SNO-14100](#) [SD-112S](#) [MUP-C7804-1](#) [KH-TF-07DT](#)